

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

**TC74ACT240P, TC74ACT240F, TC74ACT240FW, TC74ACT240FT**  
**TC74ACT244P, TC74ACT244F, TC74ACT244FW, TC74ACT244FT**

**OCTAL BUS BUFFER**

**TC74ACT240P/F/FW/FT INVERTED, 3 - STATE OUTPUTS**  
**TC74ACT244P/F/FW/FT NON - INVERTED, 3 - STATE OUTPUTS**

The TC74ACT240 and 244 are advanced high speed CMOS OCTAL BUS BUFFERS fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

They achieve the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The 74ACT240 is an inverting 3-state buffer while the 74ACT244 is non-inverting. Both devices have two active-low output enables.

These devices are designed to be used in such applications as 3-state memory address drivers.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**FEATURES :**

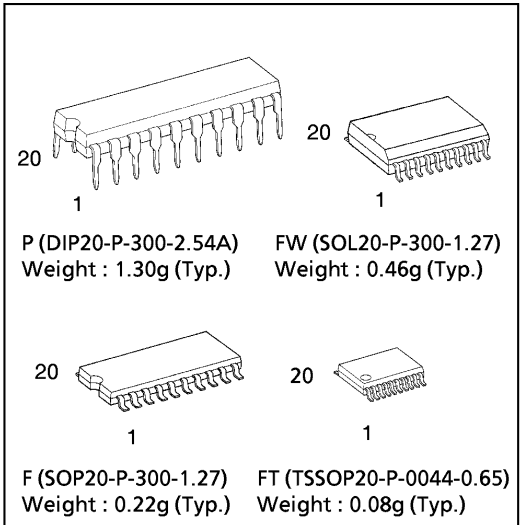
- High Speed..... $t_{pd} = 5.0ns(typ.)$  at  $V_{CC} = 5V$
- Low Power Dissipation..... $I_{CC} = 8\mu A(Max.)$  at  $T_a = 25^{\circ}C$
- Compatible with TTL outputs.... $V_{IL} = 0.8V(Max.)$   
 $V_{IH} = 2.0V(Min.)$
- Symmetrical Output Impedance... $|I_{OH}| = I_{OL} = 24mA(Min.)$   
 Capability of driving  $50\Omega$  transmission lines.
- Balanced Propagation Delays..... $t_{pLH} \approx t_{pHL}$
- Pin and Function Compatible with 74F240/244

**TRUTH TABLE**

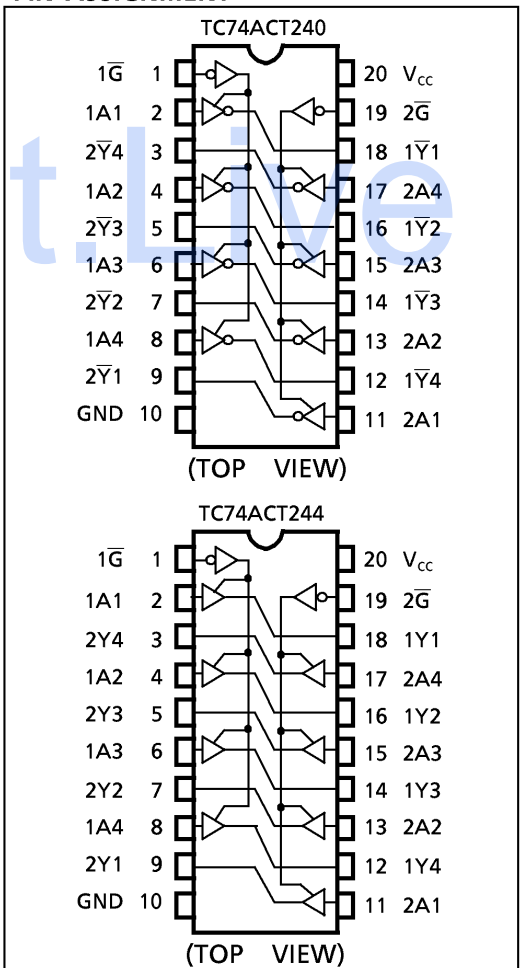
INPUTS		OUTPUTS	
$\bar{G}$	$A_n$	$Y_n(244)$	$\bar{Y}_n(240)$
L	L	L	H
L	H	H	L
H	X	Z	Z

X : Don't Care  
 Z : High Impedance

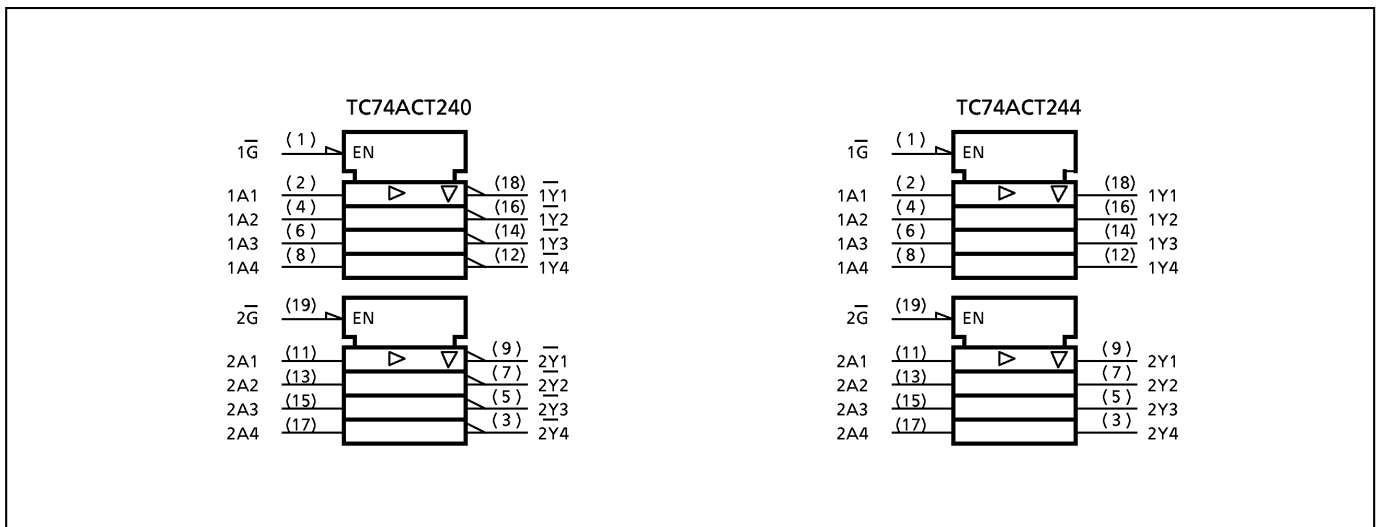
(Note) The JEDEC SOP (FW) is not available in Japan.



**PIN ASSIGNMENT**



**IEC LOGIC SYMBOL**



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7.0	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	± 20	mA
Output Diode Current	$I_{OK}$	± 50	mA
DC Output Current	$I_{OUT}$	± 50	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	± 200	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	$T_{stg}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  should be applied up to 300mW.

**RECOMMENDED OPERATING CONDITIONS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	4.5~5.5	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{opr}$	-40~85	°C
Input Rise and Fall Time	$dt/dV$	0~10	ns/V

**DC ELECTRICAL CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C			Ta = -40~85°C		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	V <sub>IH</sub>		4.5 } 5.5	2.0	—	—	2.0	—	V	
Low - Level Input Voltage	V <sub>IL</sub>		4.5 } 5.5	—	—	0.8	—	0.8	V	
High - Level Output Voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50μA	4.5	4.4	4.5	—	4.4	—	V
			I <sub>OH</sub> = -24mA	4.5	3.94	—	—	3.80	—	
			I <sub>OH</sub> = -75mA*	5.5	—	—	—	3.85	—	
Low - Level Output Voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50μA	4.5	—	0.0	0.1	—	0.1	V
			I <sub>OL</sub> = 24mA	4.5	—	—	0.36	—	0.44	
			I <sub>OL</sub> = 75mA*	5.5	—	—	—	—	1.65	
3 - State Output Off - State Current	I <sub>OZ</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5	—	—	±0.5	—	±5.0	μA	
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	±0.1	—	±1.0		
Quiescent Supply Current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	8.0	—	80.0	mA	
	I <sub>C</sub>	PER INPUT : V <sub>IN</sub> = 3.4V OTHER INPUT : V <sub>CC</sub> or GND	5.5	—	—	1.35	—	1.5		

\* : This spec indicates the capability of driving 50Ω transmission lines.  
One output should be tested at a time for a 10ms maximum duration.

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50pF, R<sub>L</sub> = 500Ω, Input t<sub>r</sub> = t<sub>f</sub> = 3ns)**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time	t <sub>pLH</sub>		5.0 ± 0.5	—	5.7	8.0	1.0	9.0	ns
	t <sub>pHL</sub>								
Output Enable Time	t <sub>pZL</sub>		5.0 ± 0.5	—	6.0	9.0	1.0	10.5	
	t <sub>pZH</sub>								
Output Disable Time	t <sub>pLZ</sub>		5.0 ± 0.5	—	5.9	8.5	1.0	10.0	
	t <sub>pHZ</sub>								
Input Capacitance	C <sub>IN</sub>		—	5	10	—	10	pF	
Output Capacitance	C <sub>OUT</sub>		—	10	—	—	—		
Power Dissipation Capacitance	C <sub>PD</sub> (1)	TC74ACT240	—	25	—	—	—		
		TC74ACT244	—	29	—	—	—		

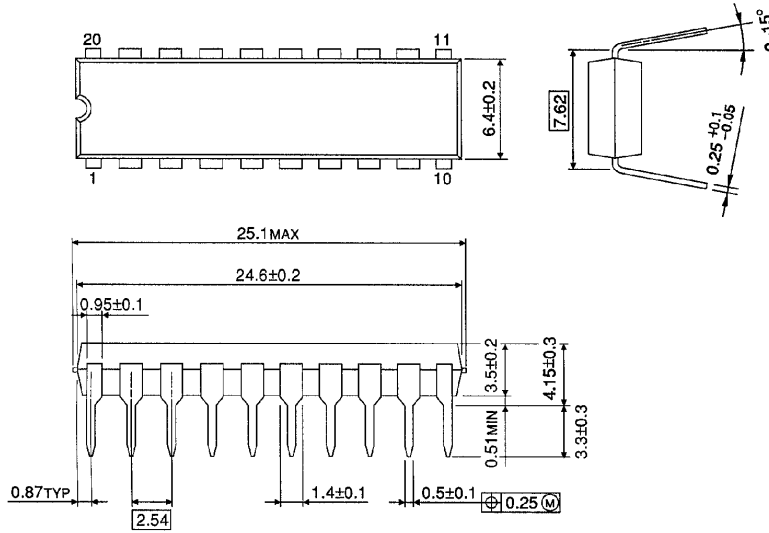
Note (1) C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 8 (\text{per bit})$$

**DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)**

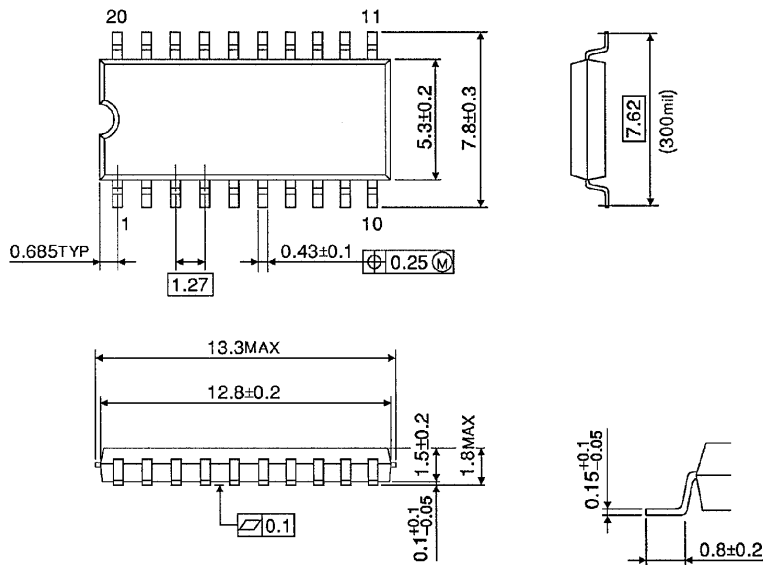
Unit in mm



Weight : 1.30g (Typ.)

**SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)**

Unit in mm

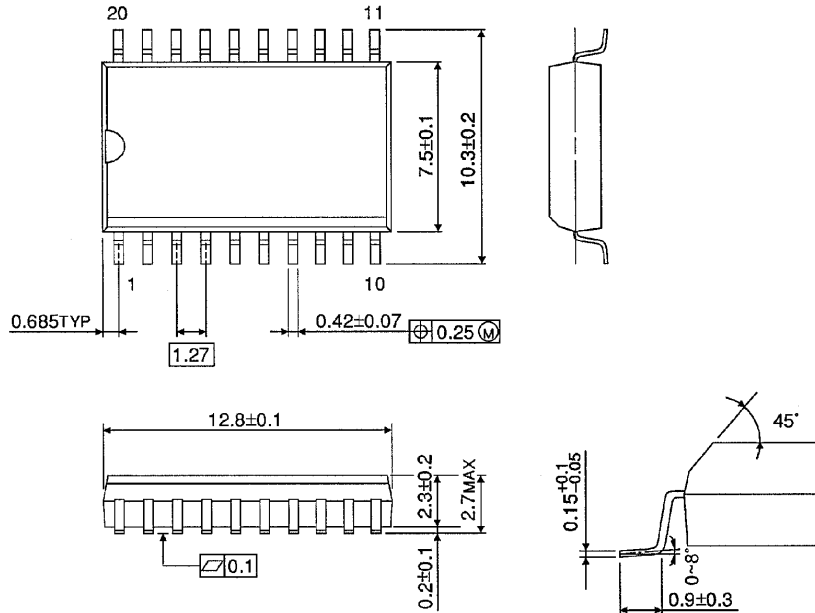


Weight : 0.22g (Typ.)

**SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)**

Unit in mm

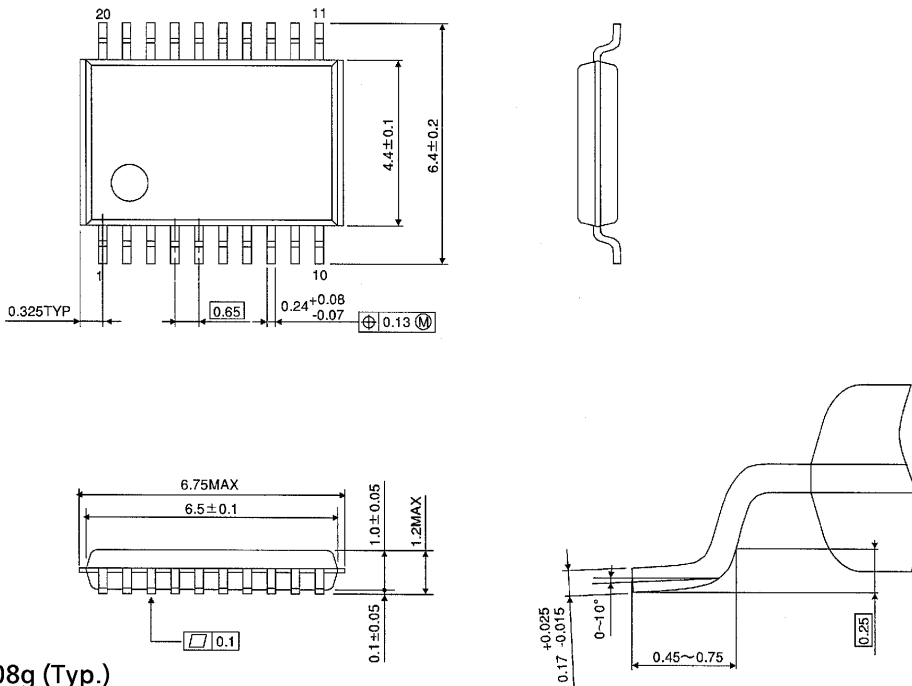
(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

**TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)**

Unit in mm



Weight : 0.08g (Typ.)

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